2SD1198, 2SD1198A

Silicon NPN epitaxial planar type darlington

For low-frequency amplification

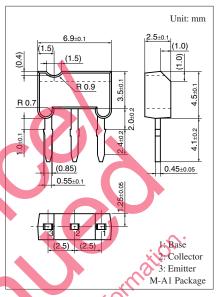
■ Features

- Forward current transfer ratio h_{FE} is designed high, which is appropriate to the driver circuit of motors and printer hammer: $h_{FE} = 4$ 000 to 20 000.
- A shunt resistor is omitted from the driver.
- M type package allowing easy automatic and manual insertion as well as stand-alone fixing to the printed circuit board.

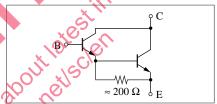
■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter		Symbol	Rating	Unit	
Collector-base voltage	2SD1198	V_{CBO}	30	V	
(Emitter open)	2SD1198A		60		
Collector-emitter voltage	2SD1198	V_{CEO}	25	V	
(Base open)	2SD1198A		50		
Emitter-base voltage (Col	V_{EBO}	5	V		
Collector current	I_{C}	1	A		
Peak collector current	I _{CP}	1.5	A		
Collector power dissipation	P_{C}	1	W		
Junction temperature	T_{j}	150	°C		
Storage temperature	T_{stg}	-55 to +150	°C		

Note) *: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion



Internal Connection



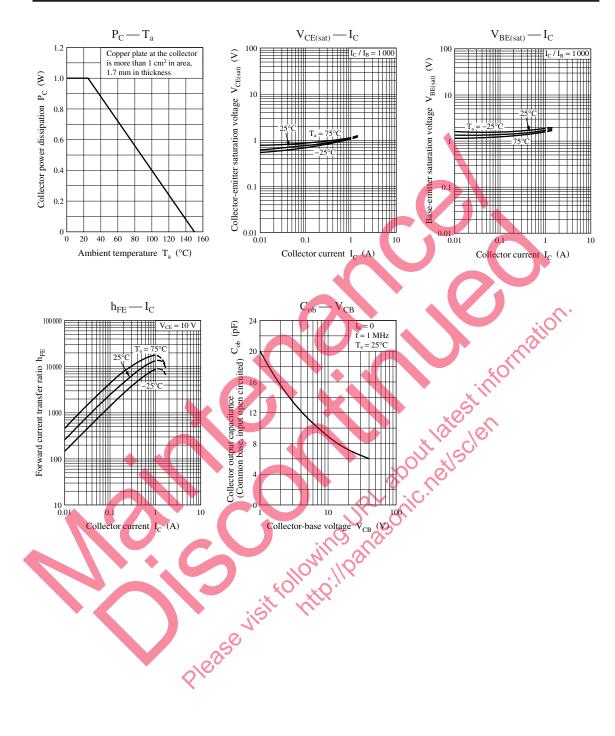
■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage 2SD1198	V _{CBO}	$I_{\rm C} = 100 \mu {\rm A} I_{\rm E} = 0$	30			V
(Emitter open) 2SD1198A		1104 1116	60			
Collector-emitter voltage 2SD1198	V _{CEO}	$I_C = 1 \text{ mA}, I_B = 0$	25			V
(Base open) 2SD1198A		in Kr	50			
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 100 \mu\text{A}, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	CI _{CBO}	$V_{CB} = 25 \text{ V}, I_{E} = 0$			100	nA
		$V_{CB} = 45 \text{ V}, I_{E} = 0$				
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 4 \text{ V}, I_C = 0$			100	nA
Forward current transfer ratio *1, 2	h _{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ A}$	4000		20 000	
Collector-emitter saturation voltage *1	V _{CE(sat)}	$I_C = 1 \text{ A}, I_B = 1 \text{ mA}$			1.8	V
Base-emitter saturation voltage *1	V _{BE(sat)}	$I_C = 1 \text{ A}, I_B = 1 \text{ mA}$			2.2	V
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		150		MHz

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

- 2. *1: Pulse measurement
 - *2: Rank classification

Rank	Q	R		
h_{FE}	4000 to 10000	8 000 to 20 000		



2 SJC00209BED

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